

## STATUS OF THE CLAIMS

The status of the claims of the present application stands as follows:

1. **(Canceled)**
2. **(Previously Presented)** An apparatus according to claim 21, wherein said rotating wafer-cleaning member comprises a brush roller having a non-filamentous cleaning surface.
3. **(Previously Presented)** An apparatus according to claim 2, wherein said brush roller comprises an electrically conductive material.
4. **(Previously Presented)** An apparatus according to claim 3, wherein said brush roller comprises a polymer filled with an electrically-conductive material.
5. **(Previously Presented)** An apparatus according to claim 4, wherein said brush roller comprises a carbon-filled perfluoroalkoxyalkane.
6. **(Canceled)**
7. **(Previously Presented)** An apparatus according to claim 3, wherein said brush roller comprises a foam rubber cleaning portion.
8. **(Canceled)**
9. **(Canceled)**
10. **(Currently Amended)** A method of removing surface contaminants from a surface of a microelectronics wafer that may have a static electrical charge thereon, comprising the steps of:
  - (a) providing a microelectronics wafer having a surface; and
  - (b) cleaning said surface of said microelectronics wafer with a conductive rotating wafer-cleaning member so as to remove at least some of the surface contaminants; and
  - (c) ~~during at least part of the time that step (a) is being performed, contacting said microelectronics wafer with a conductive member so as to simultaneously create an~~

electrical ground path between said surface and an electrical ground through said conductive rotating wafer-cleaning member.

11. (Canceled)

12. (Canceled)

13. (Canceled)

14. (Currently Amended) A method according to claim 13, wherein step (ab) includes contacting said surface with an electrically conductive wafer-cleaning brush roller having a non-filamentous cleaning surface.

15. (Canceled)

16. (Canceled)

17. (Currently Amended) A system for removing surface contaminants from a surface, comprising:

- (a) a microelectronics wafer having a surface;
- (b) an electrical ground;
- (bc) a wafer-cleaning region receiving said microelectronics wafer; and
- (ed) a conductive rotating wafer-cleaning member operatively configured to engage said surface of microelectronics wafer in said wafer cleaning region so as to remove contaminants from said surface and provide part of a grounding path between said microelectronics wafer and said electrical ground for removing electrical charge from said microelectronics wafer.;
- (d) an electrical ground; and
- (e) an electrically conductive path extending from said microelectronics wafer to said ground.

18. (Previously Presented) A system according to claim 17, wherein said rotating wafer-cleaning member comprises a brush roller having a non-filamentous cleaning surface.

19. (Canceled)

20. (Canceled)

21. (Currently Amended) An apparatus for cleaning surface contaminants from a microelectronics wafer, comprising:

- (a) a wafer cleaning region configured to receive a microelectronics wafer during cleaning;
- (b) a conductive rotating wafer-cleaning member designed to contact the microelectronics wafer during cleaning so as to remove surface contaminants from the microelectronics wafer during cleaning; and
- (c) an electrical grounding path extending from the microelectronic wafer through said conductive rotating wafer-cleaning member to an electrical ground when the apparatus is connected to the electrical ground.